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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	18
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f687t-e-ss

Device	Program Memory	Data Memory		I/O	10-bit A/D (ch)	Comparators	Timers 8/16-bit	SSP	ECCP+	EUSART
	Flash (words)	SRAM (bytes)	EEPROM (bytes)							
PIC16F631	1024	64	128	18	—	2	1/1	No	No	No
PIC16F677	2048	128	256	18	12	2	1/1	Yes	No	No
PIC16F685	4096	256	256	18	12	2	2/1	No	Yes	No
PIC16F687	2048	128	256	18	12	2	1/1	Yes	No	Yes
PIC16F689	4096	256	256	18	12	2	1/1	Yes	No	Yes
PIC16F690	4096	256	256	18	12	2	2/1	Yes	Yes	Yes

PIC16F631 Pin Diagram

20-pin PDIP, SOIC, SSOP

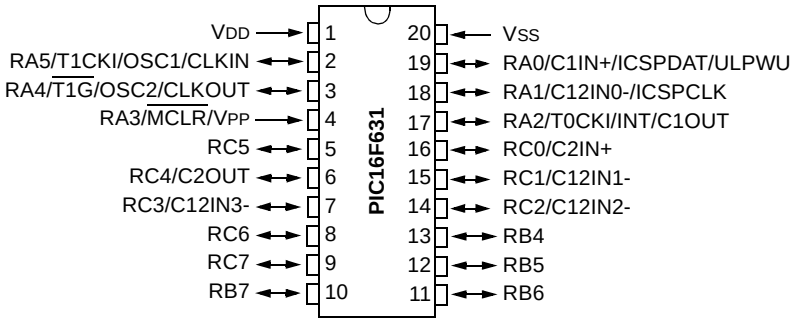


TABLE 1: PIC16F631 PIN SUMMARY

I/O	Pin	Analog	Comparators	Timers	Interrupt	Pull-up	Basic
RA0	19	AN0/ULPWU	C1IN+	—	IOC	Y	ICSPDAT
RA1	18	AN1	C12IN0-	—	IOC	Y	ICSPCLK
RA2	17	—	C1OUT	T0CKI	IOC/INT	Y	—
RA3	4	—	—	—	IOC	Y(1)	MCLR/VPP
RA4	3	—	—	T1G	IOC	Y	OSC2/CLKOUT
RA5	2	—	—	T1CKI	IOC	Y	OSC1/CLKIN
RB4	13	—	—	—	IOC	Y	—
RB5	12	—	—	—	IOC	Y	—
RB6	11	—	—	—	IOC	Y	—
RB7	10	—	—	—	IOC	Y	—
RC0	16	AN4	C2IN+	—	—	—	—
RC1	15	AN5	C12IN1-	—	—	—	—
RC2	14	AN6	C12IN2-	—	—	—	—
RC3	7	AN7	C12IN3-	—	—	—	—
RC4	6	—	C2OUT	—	—	—	—
RC5	5	—	—	—	—	—	—
RC6	8	—	—	—	—	—	—
RC7	9	—	—	—	—	—	—
—	1	—	—	—	—	—	VDD
—	20	—	—	—	—	—	VSS

Note 1: Pull-up enabled only with external MCLR configuration.

TABLE 2-1: PIC16F631/677/685/687/689/690 SPECIAL FUNCTION REGISTERS SUMMARY BANK 0

Addr	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Page
Bank 0											
00h	INDF	Addressing this location uses contents of FSR to address data memory (not a physical register)								xxxx xxxx	43,200
01h	TMR0	Timer0 Module Register								xxxx xxxx	79,200
02h	PCL	Program Counter's (PC) Least Significant Byte								0000 0000	43,200
03h	STATUS	IRP	RP1	RP0	$\overline{TO}$	$\overline{PD}$	Z	DC	C	0001 1xxx	35,200
04h	FSR	Indirect Data Memory Address Pointer								xxxx xxxx	43,200
05h	PORTA(7)	—	—	RA5	RA4	RA3	RA2	RA1	RA0	--xx xxxx	57,200
06h	PORTB(7)	RB7	RB6	RB5	RB4	—	—	—	—	xxxx ----	67,200
07h	PORTC(7)	RC7	RC6	RC5	RC4	RC3	RC2	RC1	RC0	xxxx xxxx	74,200
08h	—	Unimplemented								—	—
09h	—	Unimplemented								—	—
0Ah	PCLATH	—	—	—	Write Buffer for upper 5 bits of Program Counter					---0 0000	43,200
0Bh	INTCON	GIE	PEIE	T0IE	INTE	RABIE	T0IF	INTF	RABIF(1)	0000 000x	37,200
0Ch	PIR1	—	ADIF(4)	RCIF(2)	TXIF(2)	SSPIF(5)	CCP1IF(3)	TMR2IF(3)	TMR1IF	-000 0000	40,200
0Dh	PIR2	OSFIF	C2IF	C1IF	EEIF	—	—	—	—	0000 ----	41,200
0Eh	TMR1L	Holding Register for the Least Significant Byte of the 16-bit TMR1 Register								xxxx xxxx	85,200
0Fh	TMR1H	Holding Register for the Most Significant Byte of the 16-bit TMR1 Register								xxxx xxxx	85,200
10h	T1CON	T1GINV	TMR1GE	T1CKPS1	T1CKPS0	T1OSCEN	$\overline{T1SYNC}$	TMR1CS	TMR1ON	0000 0000	87,200
11h	TMR2(3)	Timer2 Module Register								0000 0000	89,200
12h	T2CON(3)	—	TOUTPS3	TOUTPS2	TOUTPS1	TOUTPS0	TMR2ON	T2CKPS1	T2CKPS0	-000 0000	90,200
13h	SSPBUF(5)	Synchronous Serial Port Receive Buffer/Transmit Register								xxxx xxxx	178,200
14h	SSPCON(5, 6)	WCOL	SSPOV	SSPEN	CKP	SSPM3	SSPM2	SSPM1	SSPM0	0000 0000	177,200
15h	CCPR1L(3)	Capture/Compare/PWM Register 1 (LSB)								xxxx xxxx	126,200
16h	CCPR1H(3)	Capture/Compare/PWM Register 1 (MSB)								xxxx xxxx	126,200
17h	CCP1CON(3)	P1M1	P1M0	DC1B1	DC1B0	CCP1M3	CCP1M2	CCP1M1	CCP1M0	0000 0000	125,200
18h	RCSTA(2)	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D	0000 000x	158,200
19h	TXREG(2)	EUSART Transmit Data Register								0000 0000	150
1Ah	RCREG(2)	EUSART Receive Data Register								0000 0000	155
1Bh	—	Unimplemented								—	—
1Ch	PWM1CON(3)	PRSEN	PDC6	PDC5	PDC4	PDC3	PDC2	PDC1	PDC0	0000 0000	143,200
1Dh	ECCPAS(3)	ECCPASE	ECCPAS2	ECCPAS1	ECCPAS0	PSSAC1	PSSAC0	PSSBD1	PSSBD0	0000 0000	140,200
1Eh	ADRESH(4)	A/D Result Register High Byte								xxxx xxxx	113,200
1Fh	ADCON0(4)	ADFM	VCFG	CHS3	CHS2	CHS1	CHS0	GO/$\overline{DONE}$	ADON	0000 0000	111,200

Legend: – = Unimplemented locations read as '0', u = unchanged, x = unknown, q = value depends on condition, shaded = unimplemented

Note 1: $\overline{MCLR}$ and WDT Reset do not affect the previous value data latch. The RABIF bit will be cleared upon Reset but will set again if the mismatch exists.

2: PIC16F687/PIC16F689/PIC16F690 only.

3: PIC16F685/PIC16F690 only.

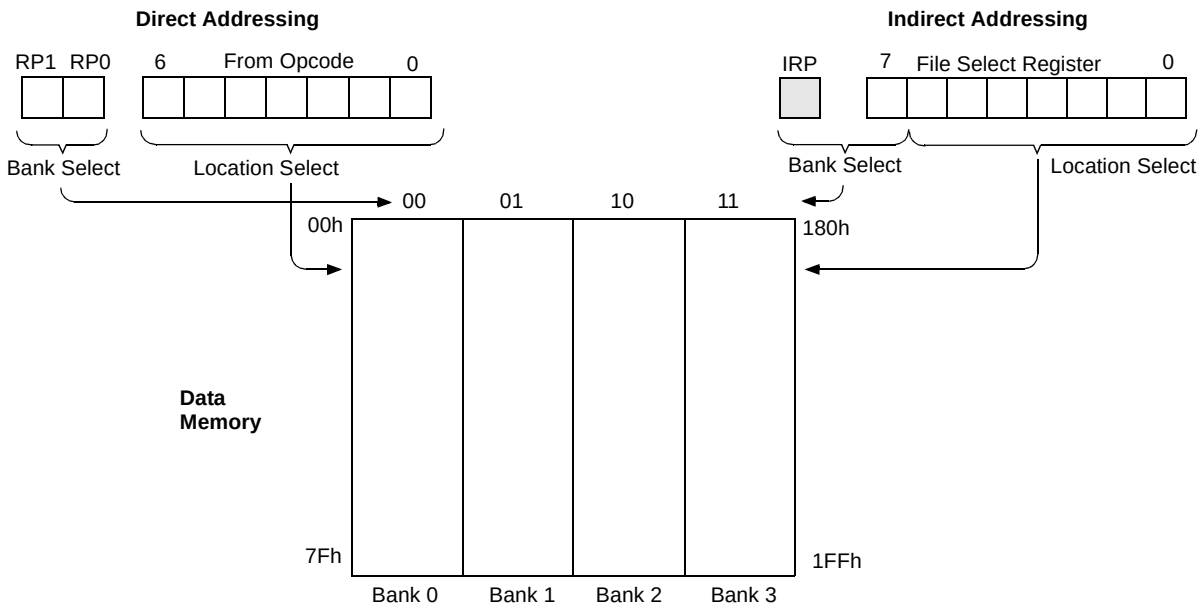
4: PIC16F677/PIC16F685/PIC16F687/PIC16F689/PIC16F690 only.

5: PIC16F677/PIC16F687/PIC16F689/PIC16F690 only.

6: When SSPCON register bits SSPM<3:0> = 1001, any reads or writes to the SSPADD SFR address are accessed through the SSPMSK register. See Registers 13-2 and 13-3 for more detail.

7: Port pins with analog functions controlled by the ANSEL and ANSELH registers will read '0' immediately after a Reset even though the data latches are either undefined (POR) or unchanged (other Resets).

FIGURE 2-10: DIRECT/INDIRECT ADDRESSING PIC16F631/677/685/687/689/690



For memory map detail, see Figures 2-6, 2-7 and 2-8.

3.7.3 CHECKING TWO-SPEED CLOCK STATUS

Checking the state of the OSTS bit of the OSCCON register will confirm if the microcontroller is running from the external clock source, as defined by the FOSC<2:0> bits in the Configuration Word register (CONFIG), or the internal oscillator.

FIGURE 3-7: TWO-SPEED START-UP

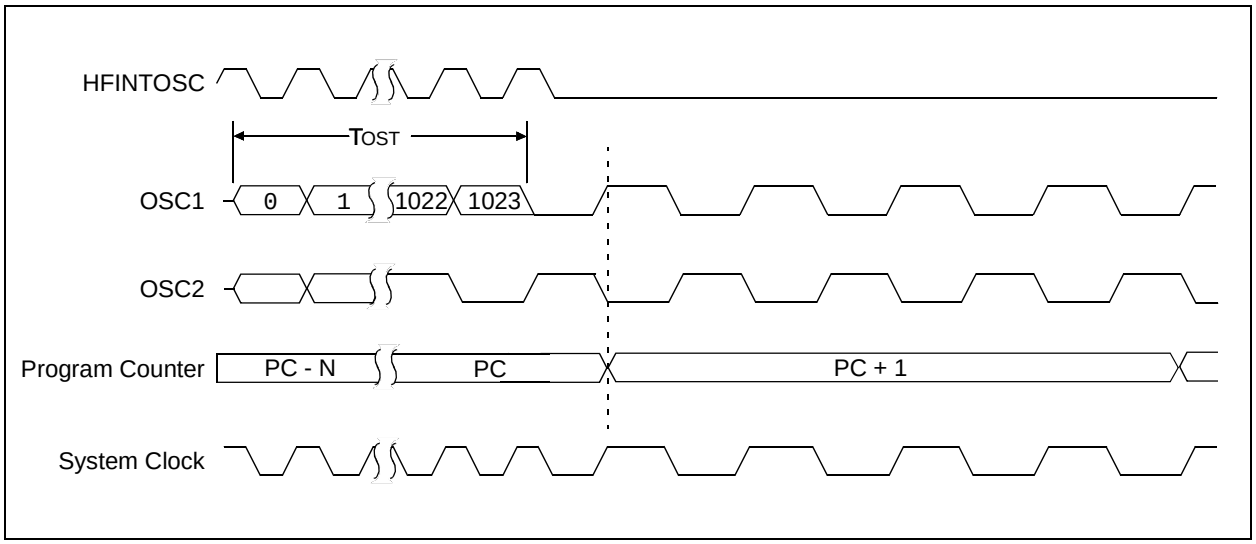
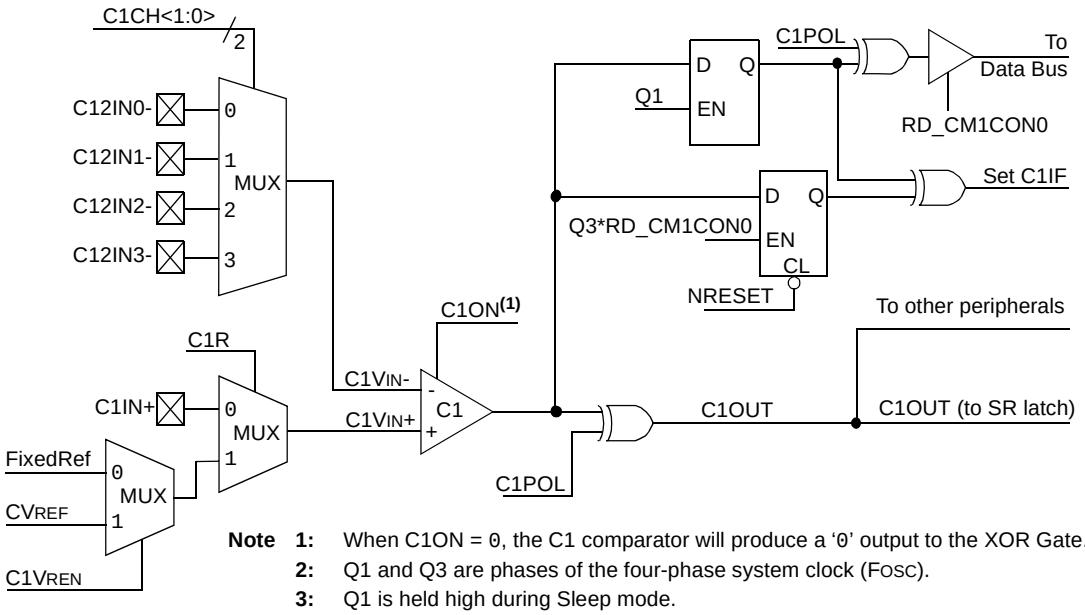
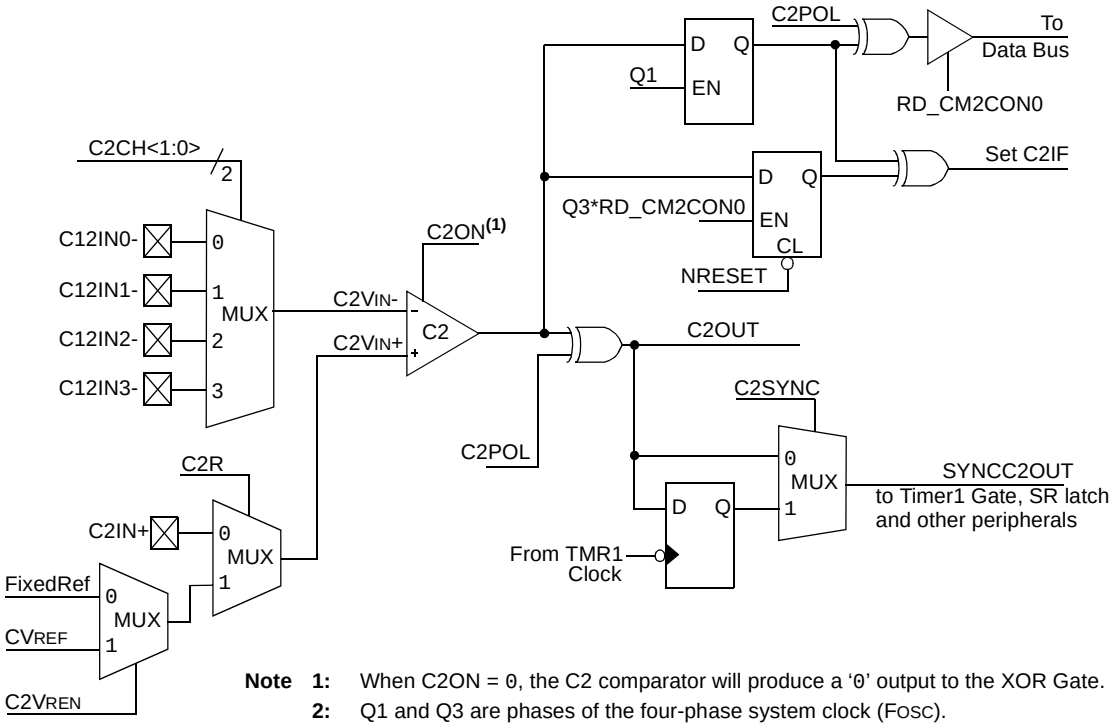


FIGURE 8-2: COMPARATOR C1 SIMPLIFIED BLOCK DIAGRAM



Note 1: When C1ON = 0, the C1 comparator will produce a '0' output to the XOR Gate.
2: Q1 and Q3 are phases of the four-phase system clock (FOSC).
3: Q1 is held high during Sleep mode.

FIGURE 8-3: COMPARATOR C2 SIMPLIFIED BLOCK DIAGRAM



Note 1: When C2ON = 0, the C2 comparator will produce a '0' output to the XOR Gate.
2: Q1 and Q3 are phases of the four-phase system clock (FOSC).
3: Q1 is held high during Sleep mode.

REGISTER 9-1: ADCON0: A/D CONTROL REGISTER 0

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ADFM	VCFG	CHS3	CHS2	CHS1	CHS0	GO/$\overline{\text{DONE}}$	ADON
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **ADFM:** A/D Conversion Result Format Select bit
1 = Right justified
0 = Left justified

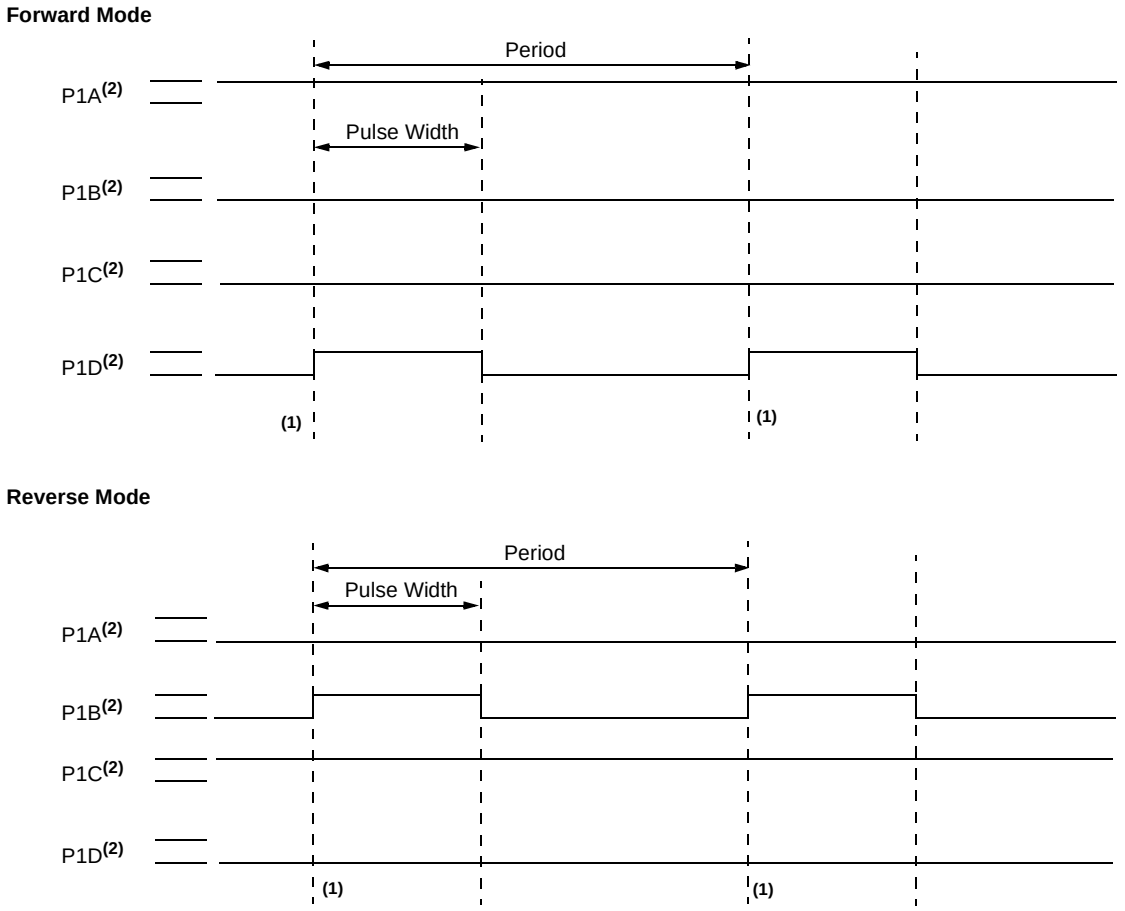
bit 6 **VCFG:** Voltage Reference bit
1 = V_{REF} pin
0 = V_{DD}

bit 5-2 **CHS<3:0>: Analog Channel Select bits**
0000 = AN0
0001 = AN1
0010 = AN2
0011 = AN3
0100 = AN4
0101 = AN5
0110 = AN6
0111 = AN7
1000 = AN8
1001 = AN9
1010 = AN10
1011 = AN11
1100 = CV_{REF}
1101 = 0.6V Fixed Voltage Reference
1110 = Reserved. Do not use.
1111 = Reserved. Do not use.

bit 1 **GO/$\overline{\text{DONE}}$:** A/D Conversion Status bit
1 = A/D conversion cycle in progress. Setting this bit starts an A/D conversion cycle.
This bit is automatically cleared by hardware when the A/D conversion has completed.
0 = A/D conversion completed/not in progress

bit 0 **ADON:** ADC Enable bit
1 = ADC is enabled
0 = ADC is disabled and consumes no operating current

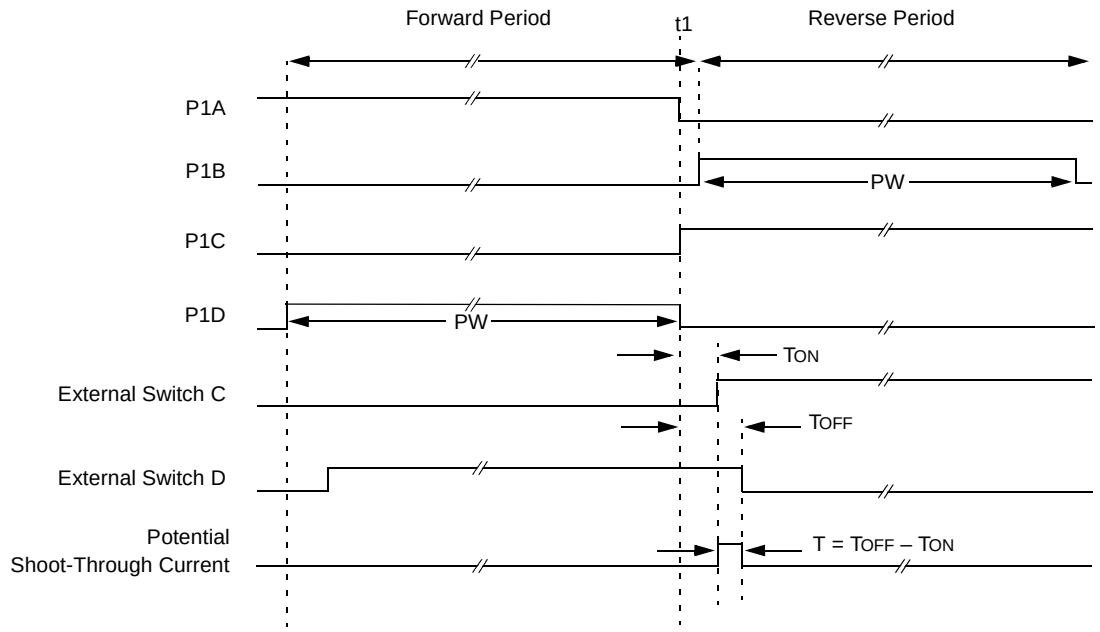
FIGURE 11-11: EXAMPLE OF FULL-BRIDGE PWM OUTPUT



Note 1: At this time, the TMR2 register is equal to the PR2 register.

2: Output signal is shown as active-high.

FIGURE 11-13: EXAMPLE OF PWM DIRECTION CHANGE AT NEAR 100% DUTY CYCLE



Note 1: All signals are shown as active-high.

2: TON is the turn-on delay of power switch QC and its driver.

3: TOFF is the turn-off delay of power switch QD and its driver.

11.4.3 START-UP CONSIDERATIONS

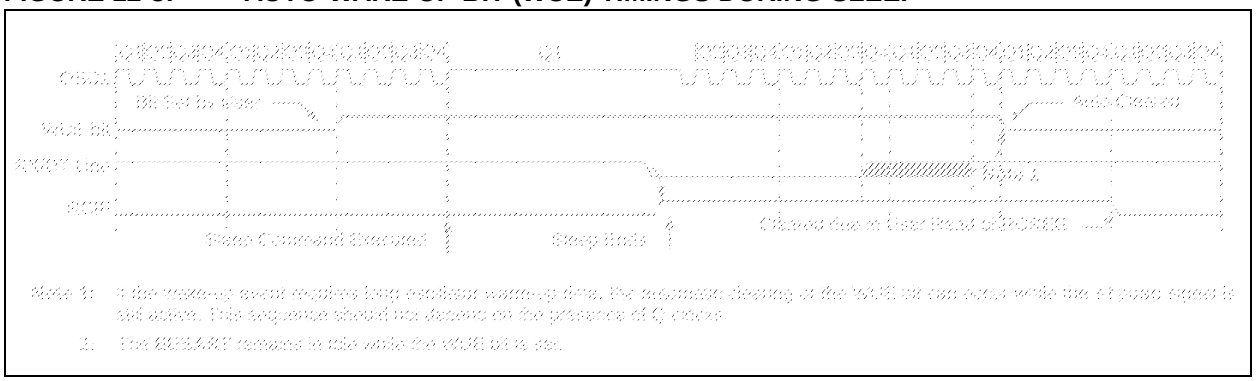
When any PWM mode is used, the application hardware must use the proper external pull-up and/or pull-down resistors on the PWM output pins.

Note:	When the microcontroller is released from Reset, all of the I/O pins are in the high-impedance state. The external circuits must keep the power switch devices in the OFF state until the microcontroller drives the I/O pins with the proper signal levels or activates the PWM output(s).

The CCP1M<1:0> bits of the CCP1CON register allow the user to choose whether the PWM output signals are active-high or active-low for each pair of PWM output pins (P1A/P1C and P1B/P1D). The PWM output polarities must be selected before the PWM pin output drivers are enabled. Changing the polarity configuration while the PWM pin output drivers are enabled is not recommended since it may result in damage to the application circuits.

The P1A, P1B, P1C and P1D output latches may not be in the proper states when the PWM module is initialized. Enabling the PWM pin output drivers at the same time as the Enhanced PWM modes may cause damage to the application circuit. The Enhanced PWM modes must be enabled in the proper Output mode and complete a full PWM cycle before enabling the PWM pin output drivers. The completion of a full PWM cycle is indicated by the TMR2IF bit of the PIR1 register being set as the second PWM period begins.

FIGURE 12-8: AUTO-WAKE-UP BIT (WUE) TIMINGS DURING SLEEP



12.3.3 BREAK CHARACTER SEQUENCE

The EUSART module has the capability of sending the special Break character sequences that are required by the LIN bus standard. A Break character consists of a Start bit, followed by 12 ‘0’ bits and a Stop bit.

To send a Break character, set the SENDB and TXEN bits of the TXSTA register. The Break character transmission is then initiated by a write to the TXREG. The value of data written to TXREG will be ignored and all ‘0’s will be transmitted.

The SENDB bit is automatically reset by hardware after the corresponding Stop bit is sent. This allows the user to preload the transmit FIFO with the next transmit byte following the Break character (typically, the Sync character in the LIN specification).

The TRMT bit of the TXSTA register indicates when the transmit operation is active or Idle, just as it does during normal transmission. See Figure 12-9 for the timing of the Break character sequence.

12.3.3.1 Break and Sync Transmit Sequence

The following sequence will start a message frame header made up of a Break, followed by an auto-baud Sync byte. This sequence is typical of a LIN bus master.

1. Configure the EUSART for the desired mode.
2. Set the TXEN and SENDB bits to enable the Break sequence.
3. Load the TXREG with a dummy character to initiate transmission (the value is ignored).
4. Write ‘55h’ to TXREG to load the Sync character into the transmit FIFO buffer.
5. After the Break has been sent, the SENDB bit is reset by hardware and the Sync character is then transmitted.

When the TXREG becomes empty, as indicated by the TXIF, the next data byte can be written to TXREG.

12.3.4 RECEIVING A BREAK CHARACTER

The Enhanced EUSART module can receive a Break character in two ways.

The first method to detect a Break character uses the FERR bit of the RCSTA register and the Received data as indicated by RCREG. The Baud Rate Generator is assumed to have been initialized to the expected baud rate.

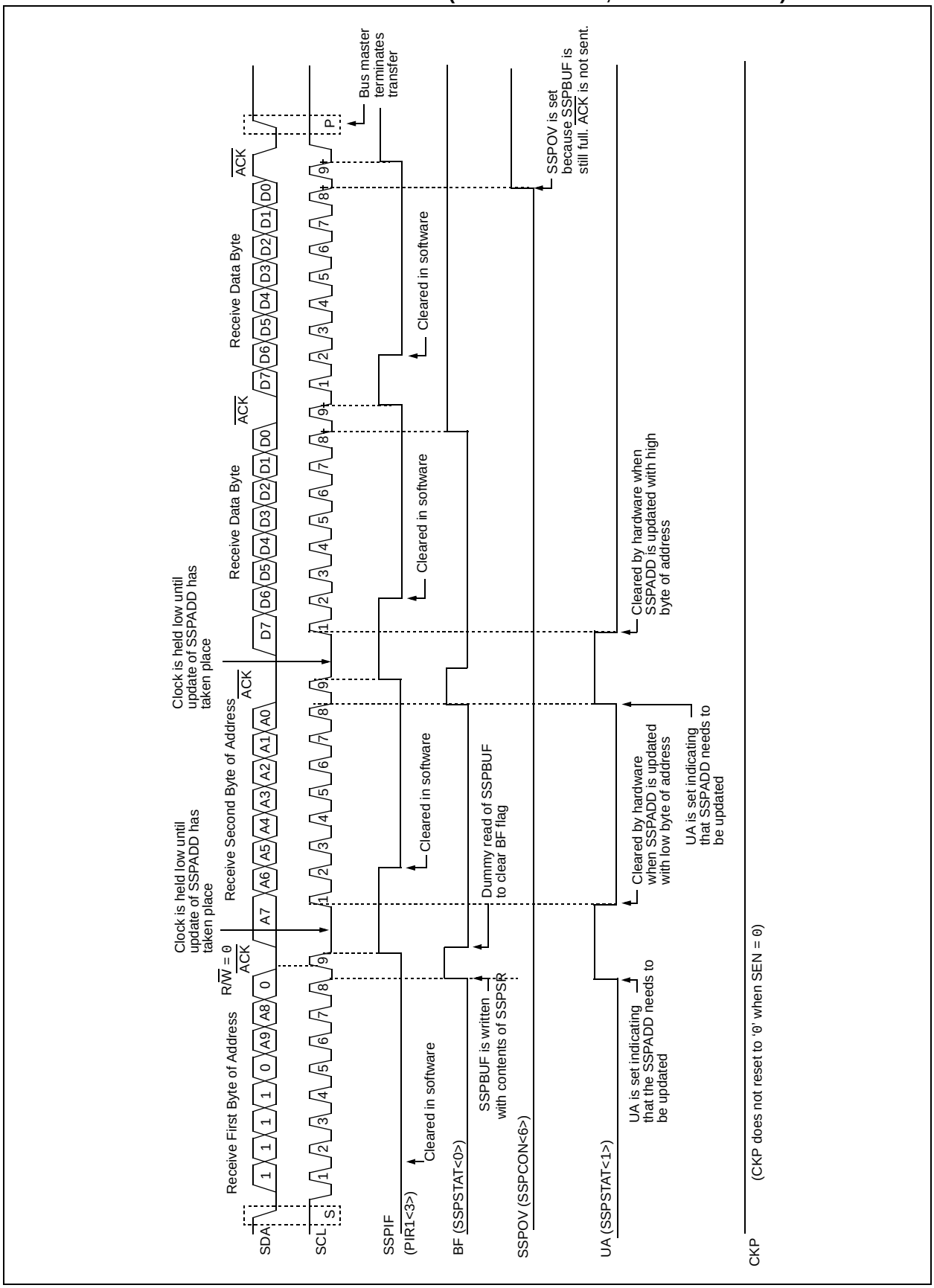
A Break character has been received when;

- RCIF bit is set
- FERR bit is set
- RCREG = 00h

The second method uses the Auto-Wake-up feature described in **Section 12.3.2 “Auto-Wake-up on Break”**. By enabling this feature, the EUSART will sample the next two transitions on RX/DT, cause an RCIF interrupt, and receive the next data byte followed by another interrupt.

Note that following a Break character, the user will typically want to enable the Auto-Baud Detect feature. For both methods, the user can set the ABDEN bit of the BAUDCTL register before placing the EUSART in Sleep mode.

FIGURE 13-11: I^2C™ SLAVE MODE TIMING (TRANSMISSION, 10-BIT ADDRESS)



14.2.5 TIME-OUT SEQUENCE

On power-up, the time-out sequence is as follows: first, PWRT time-out is invoked after POR has expired, then OST is activated after the PWRT time-out has expired. The total time-out will vary based on oscillator configuration and PWRTE bit status. For example, in EC mode with PWRTE bit erased (PWRT disabled), there will be no time-out at all. Figures 14-4, 14-5 and 14-6 depict time-out sequences. The device can execute code from the INTOSC while OST is active by enabling Two-Speed Start-up or Fail-Safe Monitor (see **Section 3.7.2 "Two-speed Start-up Sequence"** and **Section 3.8 "Fail-Safe Clock Monitor"**).

Since the time-outs occur from the POR pulse, if MCLR is kept low long enough, the time-outs will expire. Then, bringing MCLR high will begin execution immediately (see Figure 14-5). This is useful for testing purposes or to synchronize more than one PIC16F631/677/685/687/689/690 device operating in parallel.

Table 14-5 shows the Reset conditions for some special registers, while Table 14-4 shows the Reset conditions for all the registers.

14.2.6 POWER CONTROL (PCON) REGISTER

The Power Control register PCON (address 8Eh) has two Status bits to indicate what type of Reset that last occurred.

Bit 0 is BOR (Brown-out Reset). BOR is unknown on Power-on Reset. It must then be set by the user and checked on subsequent Resets to see if BOR = 0, indicating that a Brown-out has occurred. The BOR Status bit is a "don't care" and is not necessarily predictable if the brown-out circuit is disabled (BOREN<1:0> = 00 in the Configuration Word register).

Bit 1 is POR (Power-on Reset). It is a '0' on Power-on Reset and unaffected otherwise. The user must write a '1' to this bit following a Power-on Reset. On a subsequent Reset, if POR is '0', it will indicate that a Power-on Reset has occurred (i.e., VDD may have gone too low).

For more information, see **Section 4.2.4 "Ultra Low-Power Wake-up"** and **Section 14.2.4 "Brown-out Reset (BOR)"**.

TABLE 14-1: TIME-OUT IN VARIOUS SITUATIONS

Oscillator Configuration	Power-up		Brown-out Reset		Wake-up from Sleep
	PWRTE = 0	PWRTE = 1	PWRTE = 0	PWRTE = 1	
XT, HS, LP	TPWRT + 1024 • TOSC	1024 • TOSC	TPWRT + 1024 • TOSC	1024 • TOSC	1024 • TOSC
LP, T1OSCIN = 1	TPWRT	—	TPWRT	—	—
RC, EC, INTOSC	TPWRT	—	TPWRT	—	—

TABLE 14-2: STATUS/PCON BITS AND THEIR SIGNIFICANCE

POR	BOR	TO	PD	Condition
0	x	1	1	Power-on Reset
u	0	1	1	Brown-out Reset
u	u	0	u	WDT Reset
u	u	0	0	WDT Wake-up
u	u	u	u	MCLR Reset during normal operation
u	u	1	0	MCLR Reset during Sleep

Legend: u = unchanged, x = unknown

TABLE 14-3: SUMMARY OF REGISTERS ASSOCIATED WITH BROWN-OUT

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
PCON	—	—	ULPWUE	SBOREN	—	—	POR	BOR	--01 --qq	--0u --uu
STATUS	IRP	RP1	RPO	TO	PD	Z	DC	C	0001 1xxx	000q quuu

Legend: u = unchanged, x = unknown, – = unimplemented bit, reads as '0', q = value depends on condition. Shaded cells are not used by BOR.
Note 1: Other (non Power-up) Resets include MCLR Reset and Watchdog Timer Reset during normal operation.

FIGURE 14-4: TIME-OUT SEQUENCE ON POWER-UP (DELAYED $\overline{\text{MCLR}}$): CASE 1

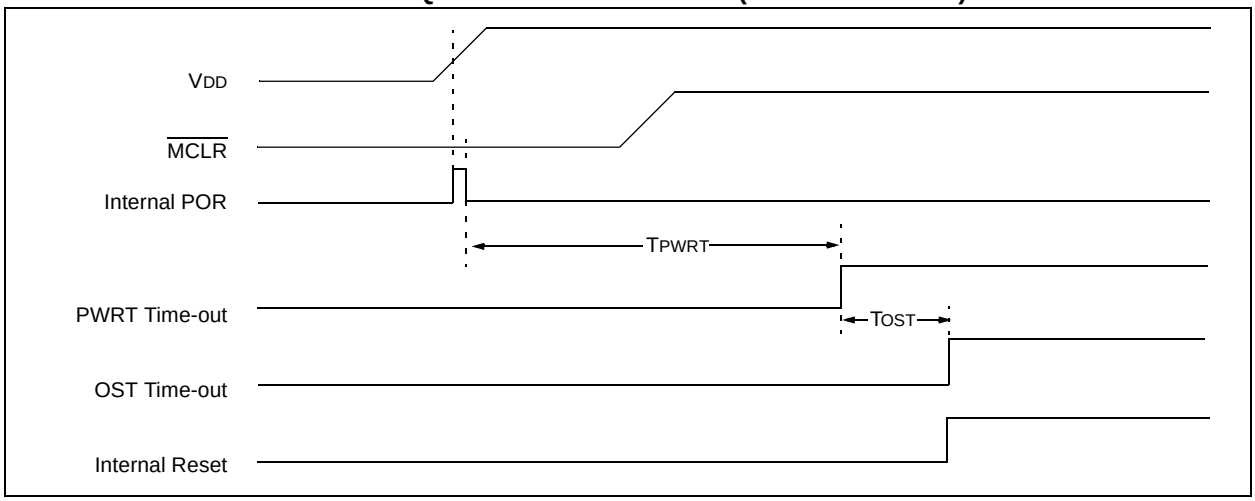


FIGURE 14-5: TIME-OUT SEQUENCE ON POWER-UP (DELAYED $\overline{\text{MCLR}}$): CASE 2

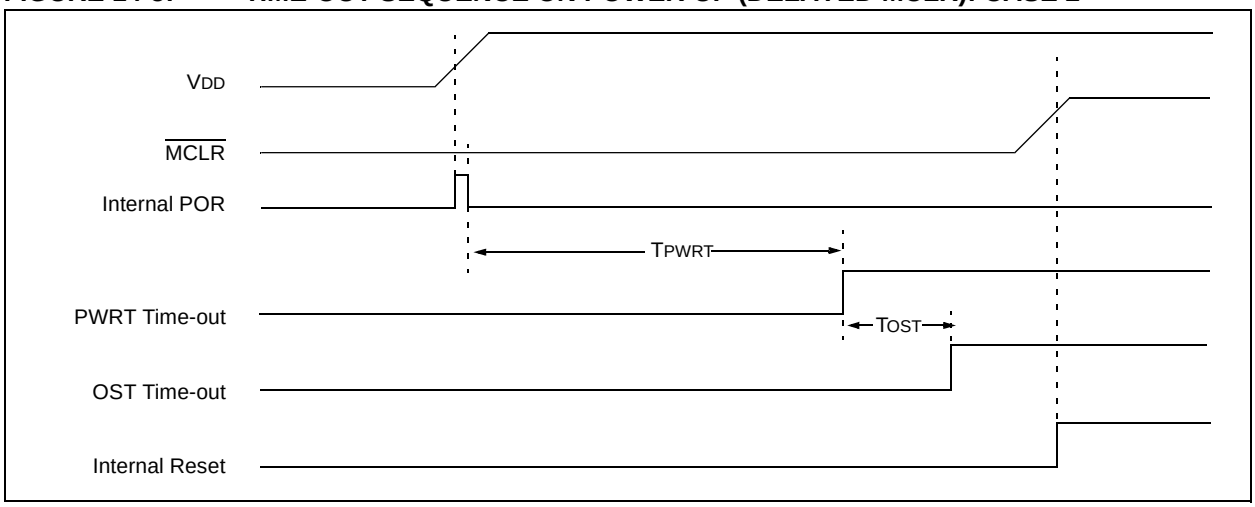


FIGURE 14-6: TIME-OUT SEQUENCE ON POWER-UP ($\overline{\text{MCLR}}$ WITH VDD)

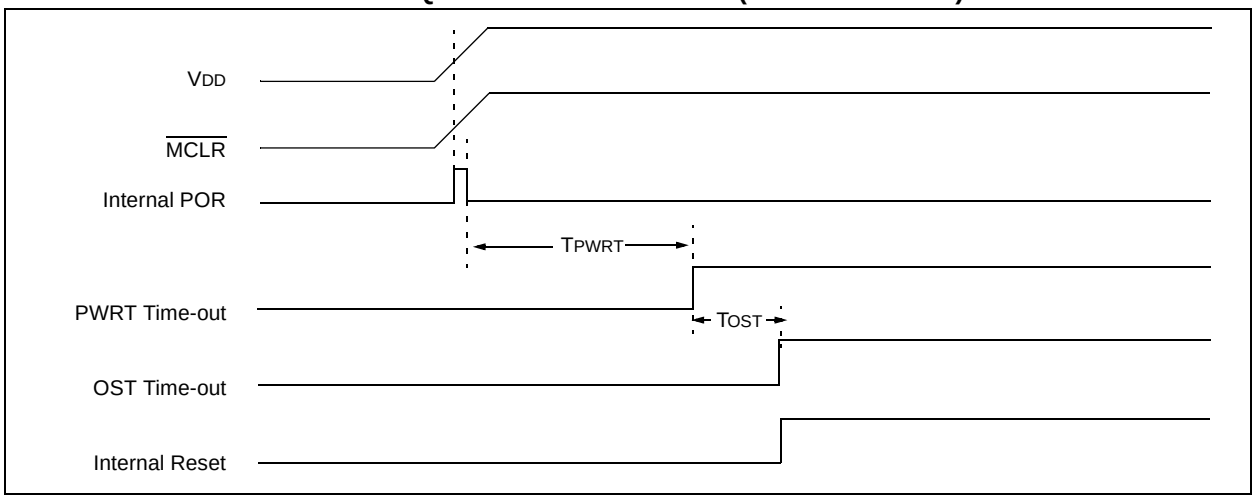
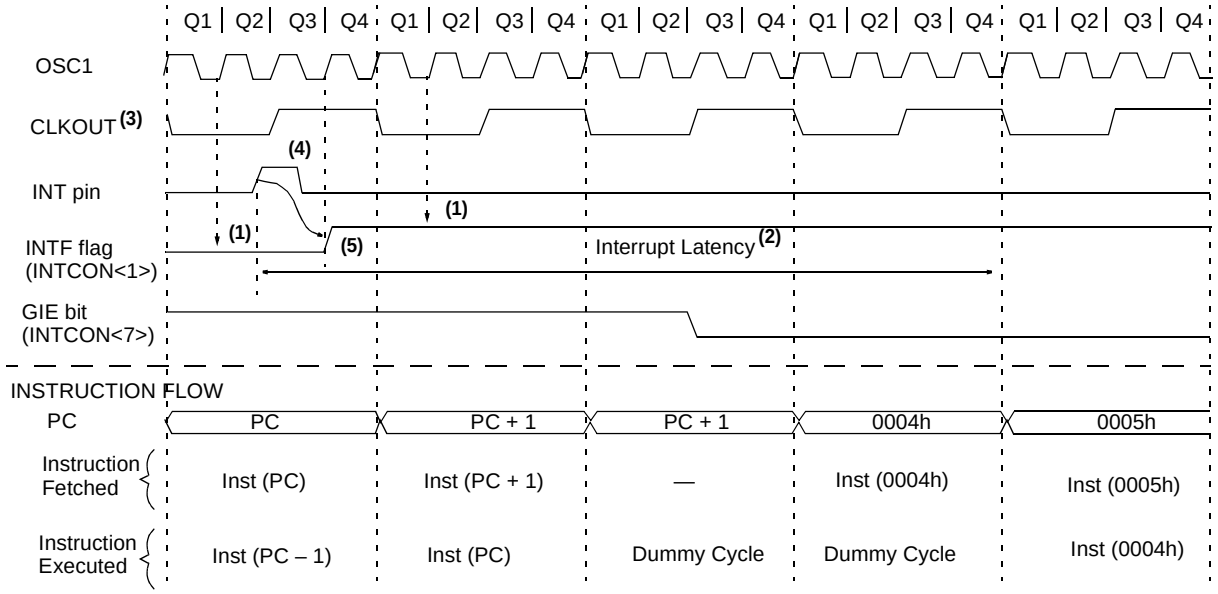


FIGURE 14-8: INT PIN INTERRUPT TIMING



Note 1: INTF flag is sampled here (every Q1).

2: Asynchronous interrupt latency = 3-4 TCY. Synchronous latency = 3 TCY, where TCY = instruction cycle time. Latency is the same whether Inst (PC) is a single cycle or a 2-cycle instruction.

3: CLKOUT is available only in INTOSC and RC Oscillator modes.

4: For minimum width of INT pulse, refer to AC specifications in **Section 17.0 "Electrical Specifications"**.

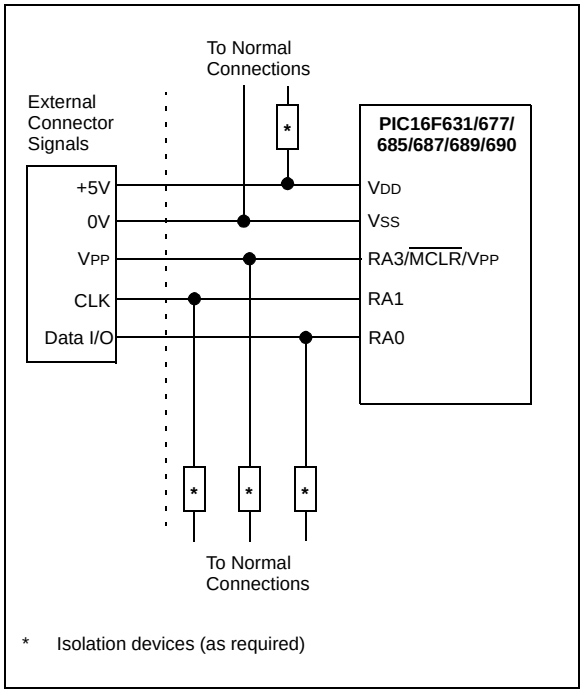
5: INTF is enabled to be set any time during the Q4-Q1 cycles.

TABLE 14-6: SUMMARY OF INTERRUPT REGISTERS

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
INTCON	GIE	PEIE	T0IE	INTE	RABIE	T0IF	INTF	RABIF	0000 000x	0000 000x
PIE1	—	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	-000 0000	-000 0000
PIE2	OSFIE	C2IE	C1IE	EEIE	—	—	—	—	0000 ----	0000 ----
PIR1	—	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	-000 0000	-000 0000
PIR2	OSFIF	C2IF	C1IF	EEIF	—	—	—	—	0000 ----	0000 ----

Legend: x = unknown, u = unchanged, – = unimplemented read as '0', q = value depends upon condition. Shaded cells are not used by the Interrupt module.

FIGURE 14-11: TYPICAL IN-CIRCUIT SERIAL PROGRAMMING CONNECTION



16.11 Demonstration/Development Boards, Evaluation Kits, and Starter Kits

A wide variety of demonstration, development and evaluation boards for various PIC MCUs and dsPIC DSCs allows quick application development on fully functional systems. Most boards include prototyping areas for adding custom circuitry and provide application firmware and source code for examination and modification.

The boards support a variety of features, including LEDs, temperature sensors, switches, speakers, RS-232 interfaces, LCD displays, potentiometers and additional EEPROM memory.

The demonstration and development boards can be used in teaching environments, for prototyping custom circuits and for learning about various microcontroller applications.

In addition to the PICDEM™ and dsPICDEM™ demonstration/development board series of circuits, Microchip has a line of evaluation kits and demonstration software for analog filter design, KEELOQ® security ICs, CAN, IrDA®, PowerSmart battery management, SEEVAL® evaluation system, Sigma-Delta ADC, flow rate sensing, plus many more.

Also available are starter kits that contain everything needed to experience the specified device. This usually includes a single application and debug capability, all on one board.

Check the Microchip web page (www.microchip.com) for the complete list of demonstration, development and evaluation kits.

16.12 Third-Party Development Tools

Microchip also offers a great collection of tools from third-party vendors. These tools are carefully selected to offer good value and unique functionality.

- Device Programmers and Gang Programmers from companies, such as SoftLog and CCS
- Software Tools from companies, such as Gimpel and Trace Systems
- Protocol Analyzers from companies, such as Saleae and Total Phase
- Demonstration Boards from companies, such as MikroElektronika, Digilent® and Olimex
- Embedded Ethernet Solutions from companies, such as EZ Web Lynx, WIZnet and IPLogika®

TABLE 17-2: OSCILLATOR PARAMETERS

Standard Operating Conditions (unless otherwise stated) Operating Temperature -40°C ≤ TA ≤ +125°C								
Param No.	**Sym.**	**Characteristic**	**Freq. Tolerance**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
OS06	TWARM	Internal Oscillator Switch when running(3)	—	—	—	2	TOSC	Slowest clock
OS07	TSC	Fail-Safe Sample Clock Period(1)	—	—	21	—	ms	LFINTOSC/64
OS08	HFOSC	Internal Calibrated HFINTOSC Frequency(2)	±1%	7.92	8.0	8.08	MHz	VDD = 3.5V, 25°C
			±2%	7.84	8.0	8.16	MHz	2.5V ≤ VDD ≤ 5.5V, 0°C ≤ TA ≤ +85°C
			±5%	7.60	8.0	8.40	MHz	2.0V ≤ VDD ≤ 5.5V, -40°C ≤ TA ≤ +85°C (Ind.), -40°C ≤ TA ≤ +125°C (Ext.)
OS09*	LFOSC	Internal Uncalibrated LFINTOSC Frequency	—	15	31	45	kHz	
OS10*	TIOSC ST	HFINTOSC Oscillator Wake-up from Sleep Start-up Time	—	5.5	12	24	µs	VDD = 2.0V, -40°C to +85°C
			—	3.5	7	14	µs	VDD = 3.0V, -40°C to +85°C
			—	3	6	11	µs	VDD = 5.0V, -40°C to +85°C

* These parameters are characterized but not tested.

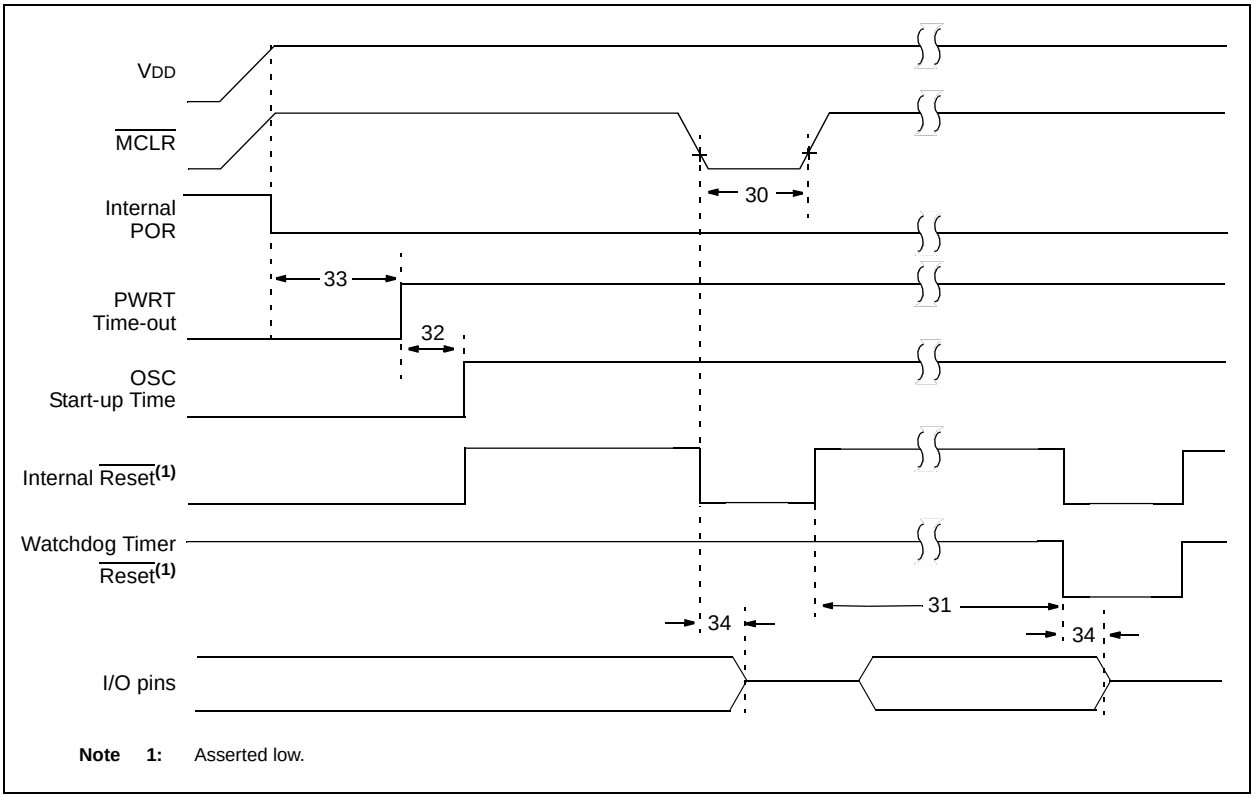
† Data in “Typ” column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at ‘min’ values with an external clock applied to the OSC1 pin. When an external clock input is used, the ‘max’ cycle time limit is ‘DC’ (no clock) for all devices.

2: To ensure these oscillator frequency tolerances, VDD and VSS must be capacitively decoupled as close to the device as possible. 0.1 µF and 0.01 µF values in parallel are recommended.

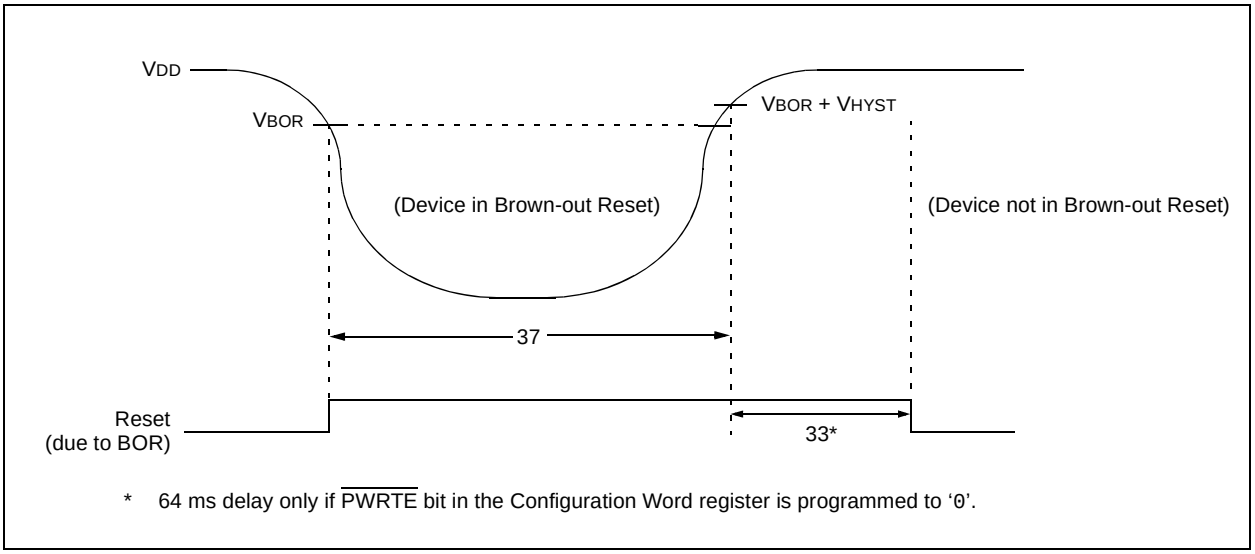
3: By design.

FIGURE 17-6: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING



Note 1: Asserted low.

FIGURE 17-7: BROWN-OUT RESET TIMING AND CHARACTERISTICS



* 64 ms delay only if PWRTE bit in the Configuration Word register is programmed to '0'.

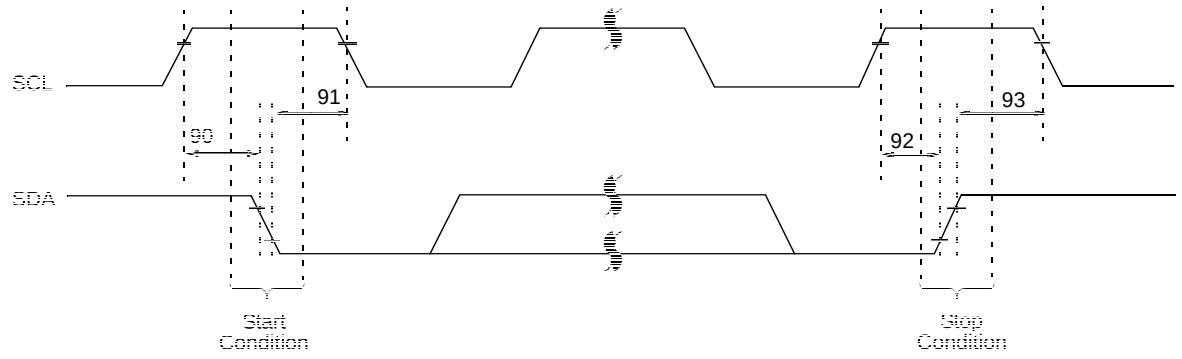
TABLE 17-12: SPI MODE REQUIREMENTS

Param No.	Symbol	Characteristic		Min.	Typ†	Max.	Units	Conditions
70*	TssL2scH, TssL2scL	$\overline{SS}\downarrow$ to SCK$\downarrow$ or SCK$\uparrow$ input		Tcy	—	—	ns	
71*	TscH	SCK input high time (Slave mode)		Tcy + 20	—	—	ns	
72*	TscL	SCK input low time (Slave mode)		Tcy + 20	—	—	ns	
73*	TdiV2scH, TdiV2scL	Setup time of SDI data input to SCK edge		100	—	—	ns	
74*	TscH2diL, TscL2diL	Hold time of SDI data input to SCK edge		100	—	—	ns	
75*	TdoR	SDO data output rise time	3.0-5.5V	—	10	25	ns	
			2.0-5.5V	—	25	50	ns	
76*	TdoF	SDO data output fall time		—	10	25	ns	
77*	TssH2doZ	$\overline{SS}\uparrow$ to SDO output high-impedance		10	—	50	ns	
78*	TscR	SCK output rise time (Master mode)	3.0-5.5V	—	10	25	ns	
			2.0-5.5V	—	25	50	ns	
79*	TscF	SCK output fall time (Master mode)		—	10	25	ns	
80*	TscH2doV, TscL2doV	SDO data output valid after SCK edge	3.0-5.5V	—	—	50	ns	
			2.0-5.5V	—	—	145	ns	
81*	TdoV2scH, TdoV2scL	SDO data output setup to SCK edge		Tcy	—	—	ns	
82*	TssL2doV	SDO data output valid after $\overline{SS}\downarrow$ edge		—	—	50	ns	
83*	TscH2ssH, TscL2ssH	$\overline{SS}\uparrow$ after SCK edge		1.5Tcy + 40	—	—	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

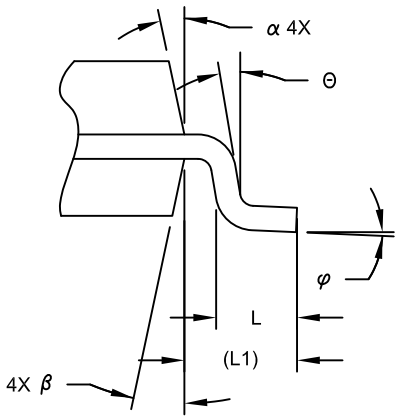
FIGURE 17-16: I^2C™ BUS START/STOP BITS TIMING



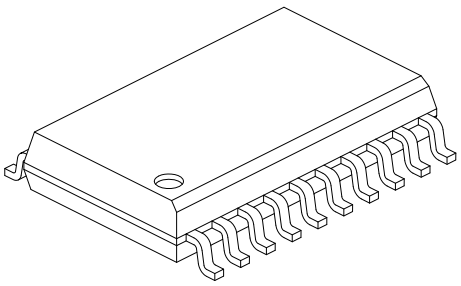
Note: Refer to Figure 17-3 for load conditions.

20-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



VIEW C



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		20	
Pitch	e		1.27 BSC	
Overall Height	A	-	-	2.65
Molded Package Thickness	A2	2.05	-	-
Standoff §	A1	0.10	-	0.30
Overall Width	E		10.30 BSC	
Molded Package Width	E1		7.50 BSC	
Overall Length	D		12.80 BSC	
Chamfer (Optional)	h	0.25	-	0.75
Foot Length	L	0.40	-	1.27
Footprint	L1		1.40 REF	
Lead Angle	Θ	0°	-	-
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.20	-	0.33
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M

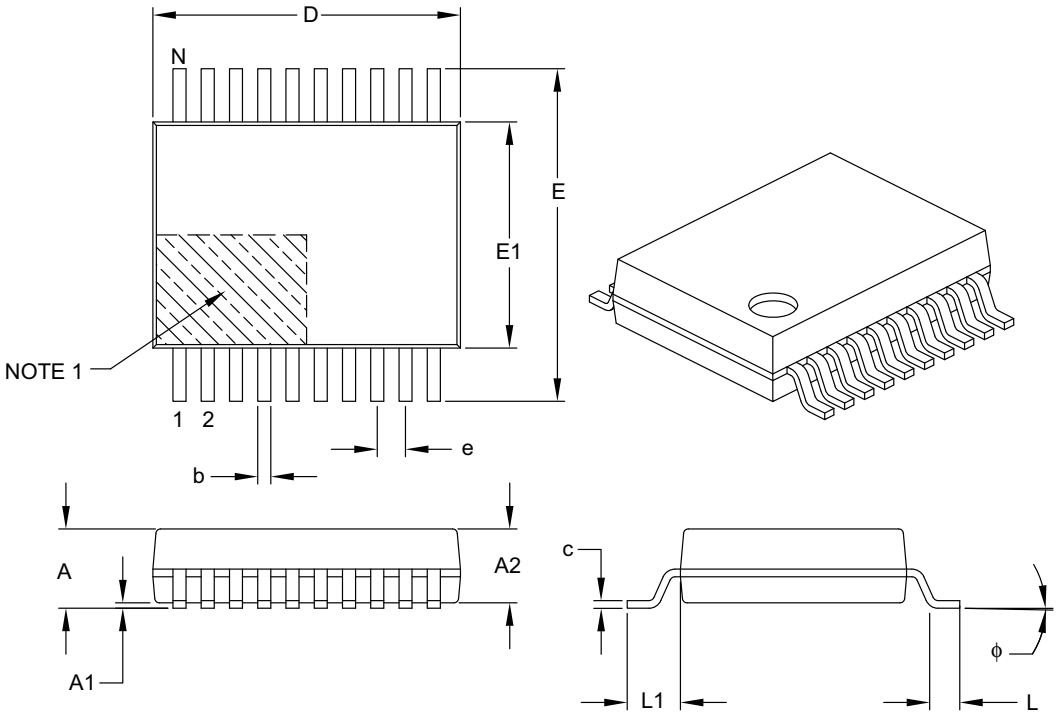
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.
5. Datums A & B to be determined at Datum H.

Microchip Technology Drawing No. C04-094C Sheet 2 of 2

20-Lead Plastic Shrink Small Outline (SS) – 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		20	
Pitch	e		0.65 BSC	
Overall Height	A	–	–	2.00
Molded Package Thickness	A2	1.65	1.75	1.85
Standoff	A1	0.05	–	–
Overall Width	E	7.40	7.80	8.20
Molded Package Width	E1	5.00	5.30	5.60
Overall Length	D	6.90	7.20	7.50
Foot Length	L	0.55	0.75	0.95
Footprint	L1		1.25 REF	
Lead Thickness	c	0.09	–	0.25
Foot Angle	ϕ	0°	4°	8°
Lead Width	b	0.22	–	0.38

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20 mm per side.
3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-072B